Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	62
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3e-3tn100i

Table 2-1. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In[1]
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output[1]

1. See Figure 2-2 for connection details.
2. Requires two PFUs.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals: Carry Generate and Carry Propagate are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM[1]	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Routing

There are many resources provided in the LatticeXP devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. The x2 and x6 resources are buffered allowing both short and long connections routing between PFUs.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

LatticeXP devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeXP devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-5 shows the 20 primary clock sources.

Figure 2-10. PLL Diagram

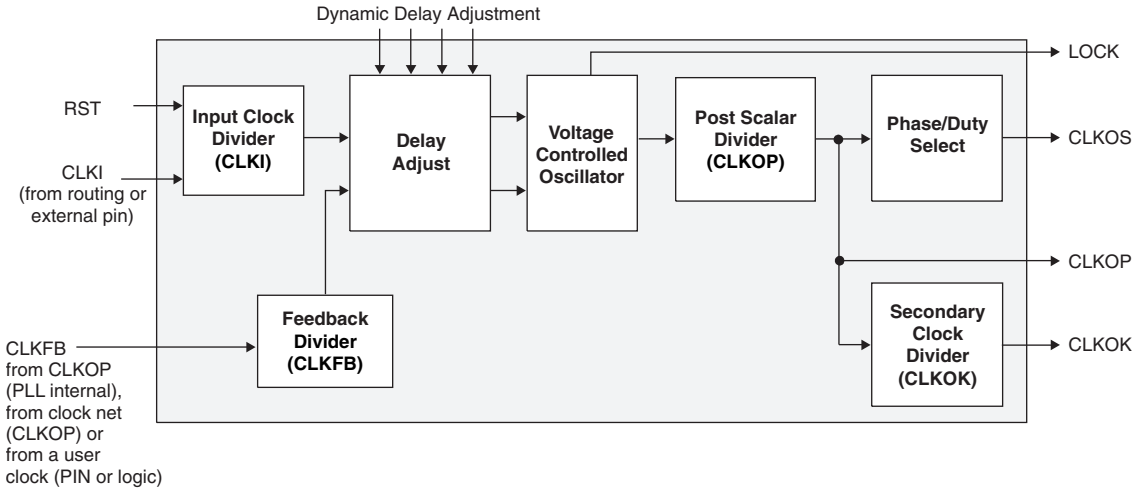


Figure 2-11 shows the available macros for the PLL. Table 2-11 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive

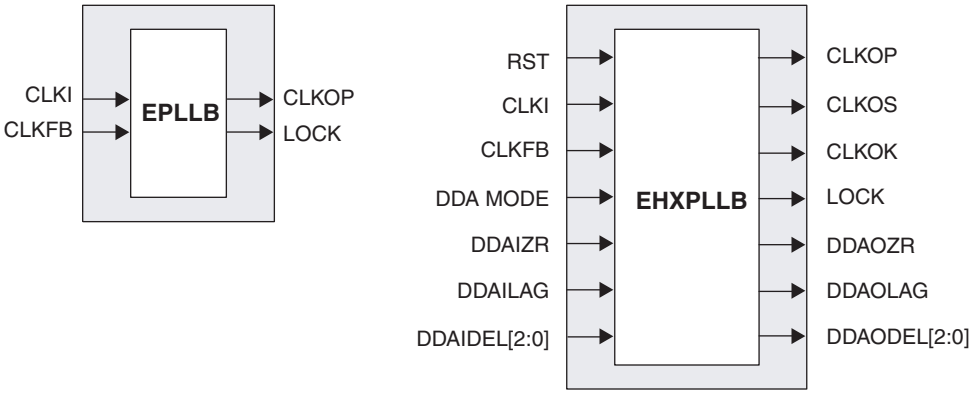
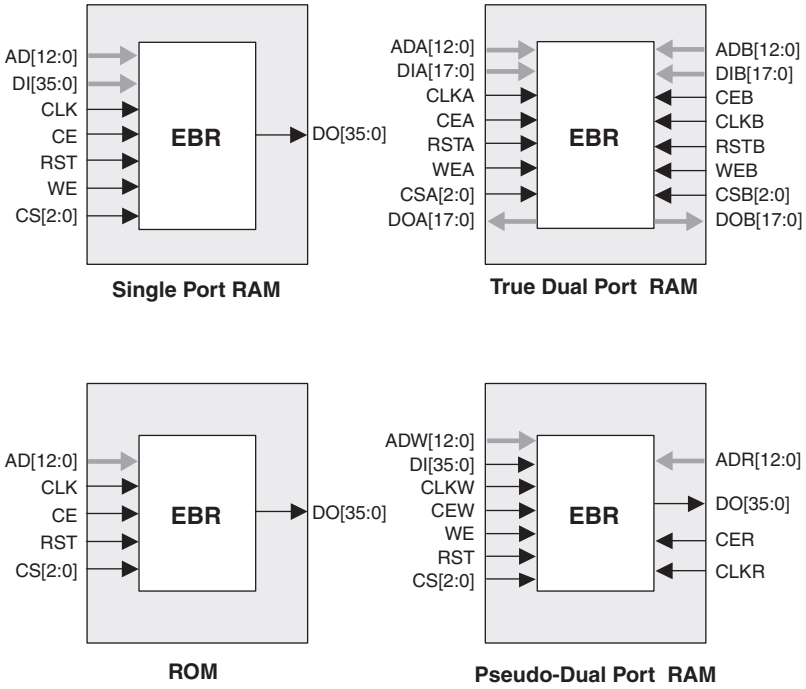


Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	“1” to reset input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	“1” indicates PLL LOCK to CLKI
DDAMODE	I	Dynamic Delay Enable. “1” Pin control (dynamic), “0”: Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. “1”: delay = 0, “0”: delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. “1”: Lag, “0”: Lead
DDAIDEL[2:0]	I	Dynamic Delay Input
DDAOZR	O	Dynamic Delay Zero Output
DDAOLAG	O	Dynamic Delay Lag/Lead Output
DDAODEL[2:0]	O	Dynamic Delay Output

Figure 2-14. sysMEM Memory Primitives



The EBR memory supports three forms of write behavior for single port or dual port operation:

1. **Normal** – data on the output appears only during read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

2. **Write Through** -þa copy of the input data appears at the output of the same port during a write cycle.þThis mode is supported for all data widths.

3. **Read-Before-Write** – when new data is being written, the old content of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-15.

LatticeXP Family Data Sheet DC and Switching Characteristics

November 2007 Data Sheet DS1001

Absolute Maximum Ratings[1, 2, 3, 4]

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied[5]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied [5]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[3]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[4]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}.
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/µs during power up when transitioning between 0V and 3.3V.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2, 4]	Input or I/O Leakage	$0 \le V_{IN} \le (V_{CCIO} - 0.2V)$	—	—	10	µA
		$(V_{CCIO} - 0.2V) < V_{IN} \le 3.6V$	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	$0 \le V_{IN} \le 0.7\ V_{CCIO}$	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold trip Points	$0 \le V_{IN} \le V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. Not applicable to SLEEPN/TOE pin.
3. T_A 25°C, f = 1.0MHz
4. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can be expected on the high-to-low transition.

Supply Current (Sleep Mode)[1, 2, 3]

Symbol	Parameter	Device	Typ.[4]	Max	Units
I_{CC}	Core Power Supply	LFXP3C	12	65	µA
		LFXP6C	14	75	µA
		LFXP10C	16	85	µA
		LFXP15C	18	95	µA
		LFXP20C	20	105	µA
I_{CCP}	PLL Power Supply (per PLL)	All LFXP 'C' Devices	1	5	µA
I_{CCAUX}	Auxiliary Power Supply	LFXP3C	2	90	µA
		LFXP6C	2	100	µA
		LFXP10C	2	110	µA
		LFXP15C	3	120	µA
		LFXP20C	4	130	µA
I_{CCIO}	Bank Power Supply[5]	LFXP3C	2	20	µA
		LFXP6C	2	22	µA
		LFXP10C	2	24	µA
		LFXP15C	3	27	µA
		LFXP20C	4	30	µA
I_{CCJ}	VCCJ Power Supply	All LFXP 'C' Devices	1	5	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency 0MHz.
3. User pattern: blank.
4. T_A=25°C, power supplies at nominal voltage.
5. Per bank.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LFXP3E	15	mA
		LFXP6E	20	mA
		LFXP10E	35	mA
		LFXP15E	45	mA
		LFXP20E	55	mA
		LFXP3C	35	mA
		LFXP6C	40	mA
		LFXP10C	70	mA
		LFXP15C	80	mA
		LFXP20C	90	mA
I_{CCP}	PLL Power Supply (per PLL)	All	8	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	22	mA
		LFXP6E/C	22	mA
		LFXP10E/C	30	mA
		LFXP15E/C	30	mA
		LFXP20E/C	30	mA
I_{CCIO}	Bank Power Supply[6]	All	2	mA
I_{CCJ}	V_{CCJ} Power Supply	All	1	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the VCCIO or GND.
3. Frequency 0MHz.
4. User pattern: blank.
5. T_A=25°C, power supplies at nominal voltage.
6. Per bank.

Initialization Supply Current[1, 2, 3, 4, 5, 6]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[7]	Units
I_{CC}	Core Power Supply	LFXP3E	40	mA
		LFXP6E	50	mA
		LFXP10E	110	mA
		LFXP15E	140	mA
		LFXP20E	250	mA
		LFXP3C	60	mA
		LFXP6C	70	mA
		LFXP10C	150	mA
		LFXP15C	180	mA
		LFXP20C	290	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15 /C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply	All	2	mA

1. Until DONE signal is active.
2. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. Typical user pattern.
6. Assume normal bypass capacitor/decoupling capacitor across the supply.
7. T_A=25°C, power supplies at nominal voltage.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

Figure 3-2. BLVDS Multi-point Output Example

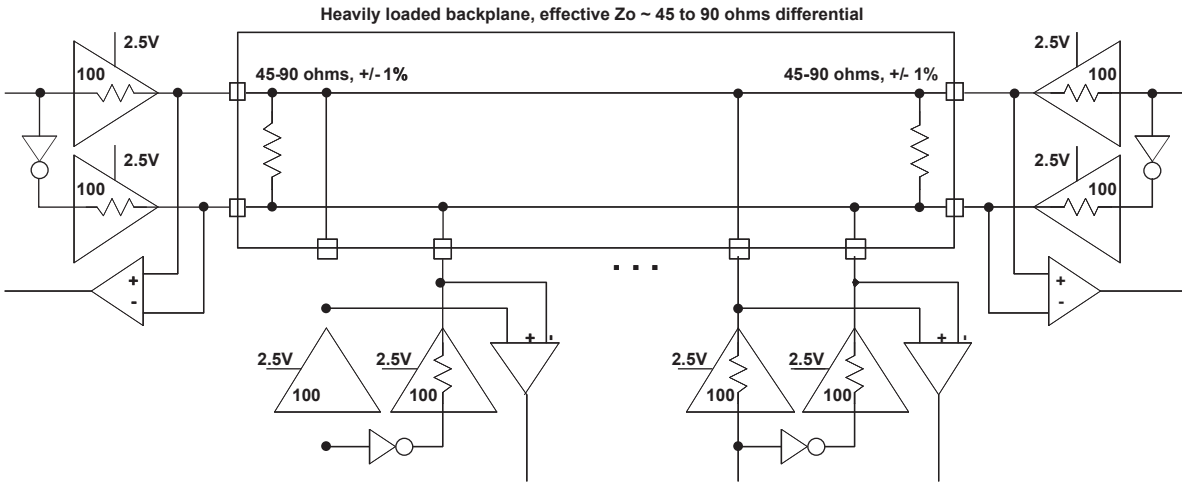


Table 3-2. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Typical		Units
		Zo = 45	Zo = 90	
Z_{OUT}	Output impedance	100	100	ohms
R_{TLEFT}	Left end termination	45	90	ohms
R_{TRIGHT}	Right end termination	45	90	ohms
V_{OH}	Output high voltage	1.375	1.48	V
V_{OL}	Output low voltage	1.125	1.02	V
V_{OD}	Output differential voltage	0.25	0.46	V
V_{CM}	Output common mode voltage	1.25	1.25	V
I_{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LatticeXP Internal Timing Parameters[1]

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 Delay (A to D Inputs to F Output)	—	0.28	—	0.34	—	0.40	ns
t_{LUT6_PFU}	LUT6 Delay (A to D Inputs to OFX Output)	—	0.44	—	0.53	—	0.63	ns
t_{LSR_PFU}	Set/Reset to Output of PFU	—	0.90	—	1.08	—	1.29	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) Input Setup Time	0.13	—	0.15	—	0.19	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) Input Hold Time	-0.04	—	-0.03	—	-0.03	—	ns
t_{SUD_PFU}	Clock to D Input Setup Time	0.13	—	0.16	—	0.19	—	ns
t_{HD_PFU}	Clock to D Input Hold Time	-0.03	—	-0.02	—	-0.02	—	ns
t_{CK2Q_PFU}	Clock to Q Delay, D-type Register Configuration	—	0.40	—	0.48	—	0.58	ns
t_{LE2Q_PFU}	Clock to Q Delay Latch Configuration	—	0.53	—	0.64	—	0.76	ns
t_{LD2Q_PFU}	D to Q Throughput Delay when Latch is Enabled	—	0.55	—	0.66	—	0.79	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.58	ns
t_{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.14	—	-0.11	—	ns
t_{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.40	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.37	—	-0.30	—	ns
t_{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	1.02	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.17	—	-0.14	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.48	—	ns
PIC Timing								
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.62	—	0.72	—	0.85	ns
t_{OUT_PIO}	Output Buffer Delay	—	2.12	—	2.54	—	3.05	ns
IOLOGIC Input/Output Timing								
t_{SUI_PIO}	Input Register Setup Time (Data Before Clock)	1.35	—	1.83	—	2.37	—	ns
t_{HI_PIO}	Input Register Hold Time (Data After Clock)	0.05	—	0.05	—	0.05	—	ns
t_{COO_PIO}	Output Register Clock to Output Delay	—	0.36	—	0.44	—	0.52	ns
t_{SUCE_PIO}	Input Register Clock Enable Setup Time	-0.09	—	-0.07	—	-0.06	—	ns
t_{HCE_PIO}	Input Register Clock Enable Hold Time	0.13	—	0.16	—	0.19	—	ns
t_{SULSR_PIO}	Set/Reset Setup Time	0.19	—	0.23	—	0.28	—	ns
t_{HLSR_PIO}	Set/Reset Hold Time	-0.14	—	-0.11	—	-0.09	—	ns
EBR Timing								
t_{CO_EBR}	Clock to Output from Address or Data	—	4.01	—	4.81	—	5.78	ns
t_{COO_EBR}	Clock to Output from EBR Output Register	—	0.81	—	0.97	—	1.17	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.13	—	-0.11	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.37	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.28	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.10	—	-0.08	—	ns

Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

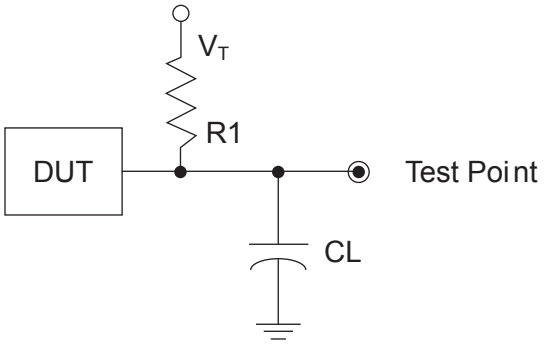


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration, the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
GSRN	I	Global RESET signal. (Active low). Any I/O pin can be configured to be GSRN.
NC	—	No connect.
GND	—	GND - Ground. Dedicated Pins.
V_{CC}	—	VCC - The power supply pins for core logic. Dedicated Pins.
V_{CCAUX}	—	V_{CCAUX} - The Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated Pins.
V_{CCP0}	—	Voltage supply pins for ULM0PLL (and LLM1PLL[1]).
V_{CCP1}	—	Voltage supply pins for URM0PLL (and LRM1PLL[1]).
GNDP0	—	Ground pins for ULM0PLL (and LLM1PLL[1]).
GNDP1	—	Ground pins for URM0PLL (and LRM1PLL[1]).
V_{CCIOx}	—	V_{CCIO} - The power supply pins for I/O bank x. Dedicated Pins.
$V_{REF1(x)}$, $V_{REF2(x)}$	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V_{REF} inputs. When not used, they may be used as I/O pins.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	—	Reference clock (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
[LOC][num]_PLL[T, C]_FB_A	—	Optional feedback (PLL) input Pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A, B, C...at each side.
PCLK[T, C]_[n:0]_[3:0]	—	Primary Clock Pads, T = true and C = complement, n per side, indexed by bank and 0,1, 2, 3 within bank.
[LOC]DQS[num]	—	DQS input Pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = Ball function number. Any pad can be configured to be DQS output.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT31B	1	C	-	PT35B	1	C	-
B15	PT31A	1	T	-	PT35A	1	T	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT28A	1	-	VREF1_1	PT34B	1	C	VREF1_1
C11	PT30A	1	T	DQS	PT34A	1	T	DQS
A14	PT29B	1	-	-	PT33B	1	-	-
B13	PT30B	1	C	-	PT32A	1	-	-
F12	PT27B	1	C	-	PT31B	1	C	-
E11	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	-	PT30B	1	C	-
C13	PT26A	1	T	D0	PT30A	1	T	D0
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C10	PT25B	1	C	D1	PT29B	1	C	D1
E10	PT25A	1	T	VREF2_1	PT29A	1	T	VREF2_1
A12	PT24B	1	C	-	PT28B	1	C	-
B12	PT24A	1	T	D2	PT28A	1	T	D2
C12	PT23B	1	C	D3	PT27B	1	C	D3
A11	PT23A	1	T	-	PT27A	1	T	-
B11	PT22B	1	C	-	PT26B	1	C	-
D11	PT22A	1	T	DQS	PT26A	1	T	DQS
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B9	PT21B	1	-	-	PT25B	1	-	-
D9	PT20A	1	-	D4	PT24A	1	-	D4
A10	PT19B	1	C	-	PT23B	1	C	-
B10	PT19A	1	T	D5	PT23A	1	T	D5
D10	PT18B	1	C	D6	PT22B	1	C	D6
A9	PT18A	1	T	-	PT22A	1	T	-
C9	PT17B	1	C	D7	PT21B	1	C	D7
C8	PT17A	1	T	-	PT21A	1	T	-
E9	PT16B	0	C	BUSY	PT20B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B8	PT16A	0	T	CS1N	PT20A	0	T	CS1N
A8	PT15B	0	C	PCLKC0_0	PT19B	0	C	PCLKC0_0
A7	PT15A	0	T	PCLKT0_0	PT19A	0	T	PCLKT0_0
B7	PT14B	0	C	-	PT18B	0	C	-
C7	PT14A	0	T	DQS	PT18A	0	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G10	GND	-	-	-	GND	-	-	-
G7	GND	-	-	-	GND	-	-	-
G8	GND	-	-	-	GND	-	-	-
G9	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-
H7	GND	-	-	-	GND	-	-	-
H8	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J7	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
U1	PL25A	6	T	LLM0_PLLT_IN_A	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
T2	PL25B	6	C	LLM0_PLLC_IN_A	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
V1	PL26A	6	T[3]	-	PL30A	6	T[3]	-	PL34A	6	T[3]	-
U2	PL26B	6	C[3]	-	PL30B	6	C[3]	-	PL34B	6	C[3]	-
W1	PL28A	6	T[3]	-	PL32A	6	T[3]	-	PL36A	6	T[3]	-
V2	PL28B	6	C[3]	-	PL32B	6	C[3]	-	PL36B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	-	-	-	GNDIO6	6	-	-
P3	PL29A	6	T	-	PL33A	6	T	-	PL37A	6	T	-
P4	PL29B	6	C	-	PL33B	6	C	-	PL37B	6	C	-
Y1	PL30A	6	T[3]	-	PL34A	6	T[3]	-	PL38A	6	T[3]	-
W2	PL30B	6	C[3]	-	PL34B	6	C[3]	-	PL38B	6	C[3]	-
R3	PL31A	6	-	VREF2_6	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL32B	6	-	-	PL36B	6	-	-	PL40B	6	-	-
T3	PL33A	6	T[3]	DQS	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
T4	PL33B	6	C[3]	-	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
V4	PL34A	6	T	LLM0_PLLT_FB_A	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
V3	PL34B	6	C	LLM0_PLLC_FB_A	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
U4	PL35A	6	T[3]	-	PL39A	6	T[3]	-	PL43A	6	T[3]	-
U3	PL35B	6	C[3]	-	PL39B	6	C[3]	-	PL43B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
W5	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
Y2	INITN	5	-	-	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y3	-	-	-	-	PB3B	5	-	-	PB7B	5	-	-
W3	-	-	-	-	PB4A	5	T	-	PB8A	5	T	-
W4	-	-	-	-	PB4B	5	C	-	PB8B	5	C	-
AA2	-	-	-	-	PB5A	5	-	-	PB9A	5	-	-
AA1	-	-	-	-	PB6B	5	-	-	PB10B	5	-	-
W6	PB2A	5	-	-	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	-	-	-	-	PB7B	5	C	-	PB11B	5	C	-
Y4	PB3A	5	T	-	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y5	PB3B	5	C	-	PB8B	5	C	-	PB12B	5	C	-
AB2	PB4A	5	T	-	PB9A	5	T	-	PB13A	5	T	-
AA3	PB4B	5	C	-	PB9B	5	C	-	PB13B	5	C	-
AB3	PB5A	5	T	-	PB10A	5	T	-	PB14A	5	T	-
AA4	PB5B	5	C	-	PB10B	5	C	-	PB14B	5	C	-
W8	PB6A	5	T	-	PB11A	5	T	-	PB15A	5	T	-
W9	PB6B	5	C	-	PB11B	5	C	-	PB15B	5	C	-
AB4	PB7A	5	T	VREF1_5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB7B	5	C	-	PB12B	5	C	-	PB16B	5	C	-
AB5	PB8A	5	-	-	PB13A	5	-	-	PB17A	5	-	-
Y6	PB9B	5	-	-	PB14B	5	-	-	PB18B	5	-	-
AA6	PB10A	5	T	DQS	PB15A	5	T	DQS	PB19A	5	T	DQS
AB6	PB10B	5	C	-	PB15B	5	C	-	PB19B	5	C	-
Y9	PB11A	5	T	-	PB16A	5	T	-	PB20A	5	T	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB19	PB37A	4	-	-	PB41A	4	-	-
AB20	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
V15	PB39A	4	T	DQS	PB43A	4	T	DQS
U15	PB39B	4	C	-	PB43B	4	C	-
Y15	PB40A	4	T	-	PB44A	4	T	-
W15	PB40B	4	C	-	PB44B	4	C	-
AA16	PB41A	4	T	-	PB45A	4	T	-
AA17	PB41B	4	C	-	PB45B	4	C	-
AA18	PB42A	4	T	-	PB46A	4	T	-
AA19	PB42B	4	C	-	PB46B	4	C	-
Y16	PB43A	4	T	-	PB47A	4	T	-
W16	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA20	PB44A	4	T	-	PB48A	4	T	-
AA21	PB44B	4	C	-	PB48B	4	C	-
Y17	PB45A	4	-	-	PB49A	4	-	-
Y18	PB46B	4	-	-	PB50B	4	-	-
Y19	PB47A	4	T	DQS	PB51A	4	T	DQS
Y20	PB47B	4	C	-	PB51B	4	C	-
V16	PB48A	4	T	-	PB52A	4	T	-
U16	PB48B	4	C	-	PB52B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
U18	-	-	-	-	PB53A	4	T	-
V18	-	-	-	-	PB53B	4	C	-
W19	-	-	-	-	PB54A	4	T	-
W18	-	-	-	-	PB54B	4	C	-
U17	-	-	-	-	PB55A	4	T	-
V17	-	-	-	-	PB55B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
W17	-	-	-	-	PB56A	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
V19	PR43A	3	-	-	PR47A	3	-	-
U20	PR42B	3	C[3]	-	PR46B	3	C[3]	-
U19	PR42A	3	T[3]	-	PR46A	3	T[3]	-
V20	PR41B	3	C	-	PR45B	3	C	-
W20	PR41A	3	T	-	PR45A	3	T	-
T17	PR40B	3	C[3]	-	PR44B	3	C[3]	-
T18	PR40A	3	T[3]	-	PR44A	3	T[3]	-
T19	PR39B	3	C[3]	-	PR43B	3	C[3]	-
T20	PR39A	3	T[3]	-	PR43A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
D18	-	-	-	-	PT55B	1	C	-
E18	-	-	-	-	PT55A	1	T	-
C19	-	-	-	-	PT54B	1	C	-
C18	-	-	-	-	PT54A	1	T	-
C21	-	-	-	-	PT53B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B21	-	-	-	-	PT53A	1	T	-
E17	PT48B	1	C	-	PT52B	1	C	-
E16	PT48A	1	T	-	PT52A	1	T	-
C17	PT47B	1	C	-	PT51B	1	C	-
D17	PT47A	1	T	DQS	PT51A	1	T	DQS
F17	PT46B	1	-	-	PT50B	1	-	-
F16	PT45A	1	-	-	PT49A	1	-	-
C16	PT44B	1	C	-	PT48B	1	C	-
D16	PT44A	1	T	-	PT48A	1	T	-
A20	PT43B	1	C	-	PT47B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B20	PT43A	1	T	-	PT47A	1	T	-
A19	PT42B	1	C	-	PT46B	1	C	-
B19	PT42A	1	T	-	PT46A	1	T	-
C15	PT41B	1	C	-	PT45B	1	C	-
D15	PT41A	1	T	-	PT45A	1	T	-
A18	PT40B	1	C	-	PT44B	1	C	-
B18	PT40A	1	T	-	PT44A	1	T	-
F15	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-
E15	PT39A	1	T	DQS	PT43A	1	T	DQS
A17	PT38B	1	-	-	PT42B	1	-	-
B17	PT37A	1	-	-	PT41A	1	-	-
E14	PT36B	1	C	-	PT40B	1	C	-
F14	PT36A	1	T	-	PT40A	1	T	-
D14	PT35B	1	C	-	PT39B	1	C	-
C14	PT35A	1	T	D0	PT39A	1	T	D0
A16	PT34B	1	C	D1	PT38B	1	C	D1
B16	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
A15	PT33B	1	C	-	PT37B	1	C	-
B15	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-
E13	PT32B	1	C	D3	PT36B	1	C	D3
D13	PT32A	1	T	-	PT36A	1	T	-
C13	PT31B	1	C	-	PT35B	1	C	-
B13	PT31A	1	T	DQS	PT35A	1	T	DQS

LatticeXP Family Data Sheet Ordering Information

December 2005 Data Sheet DS1001

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4F484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5F484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3F388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4F388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5F388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3F256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4F256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5F256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4Q208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3T100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4T100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3Q208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4Q208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4F388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K